

Computing In Memory with Tri-gate SONOS Nonvolatile Multi-level Memory

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Santa Clara, CA August 2019

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IP Portfolio

Floadia offers three kinds of eFlash IP [ZT · G1 · G2]



- In development.
- Capable of large capacity up to several MB
- Suitable for a wide range of devices including automotive LSI, IoT terminal,

AI (Computing in Memory)

- Can be embedded at 1/3 low cost, comparing to competitors, and is being adopted as a medium-range capacity Flash for Smart Phones and Automotive LSI
- Can be embedded without additional mask process.

Has High reliability as the feature, and is widely adopted for Automotive and Industrial applications

* All IPs are covered by own patents



Unique G2 characteristics make CiM possible

- Tri-Gate Structure
- Good Uniformity (no tail bit)
- Wide Ion / Ioff ratio (7 digits)
- Robust P/E endurance





> Sneak current free architecture > Precise program control 64~128 levels > 1k~10k data in/out memory array > Repeatability of setting weight



Accuracy estimation of setting weight (1M bits simulation)





- Experiment
- Target
- Vti variation

- : 40 mV / σ

: 1 *Mbit (1024 bits / output × 1000 output)* : Set bits equally at all levels 128 level, 8000 bit / each level

Target accuracy and result : Variance within the level is less than 10% to the adjacent level \rightarrow all bits succeeded (0.1 LSB@128levels)





Accuracy evaluation of Weight set (single bit)



128 levels precision capability has been confirmed.

Read operation stability (single bit)



More than 64 levels precision capability has been confirmed. Improvement to 128 levels is in progress.



Evaluation of data retention stability



The amounts of Vt shift during storage are uniform regardless of programmed level.

Comparison of Performance per Power



*GOPS: Giga-Operation Per Second TOPS: Tera-Operation Per second POPS: Peta-Operation Per Second



Summary & technology comparison			
	ReRAM	STT-MRAM	Floadia's G2
Max read current	~1uA	~10uA	<1uA
Ion/Ioff ratio	10~10 ³	2	10 ⁷
No. of level	~8	2	64~128
Sneak current	Need to care		Free
Precision control	0.5LSB@4levels : at present	Highest but for only 2 level	0.1LSB@128levels:simulat 0.5LSB@64:Si evaluatio (just started)
Resistance change mechanism	Physical structure change	Spin direction (stable)	SiN film capture/release electron (stable)
Status	R&D		 G2 cell has been availabl No restriction on migratio down to FIN process



Thank you for your attention

For further information, please visit the web site

https://www.tl

Floadia

A world class expert providing embedded Non-Volatile Technology applied to various devices such as IoT terminals and Artificial Intelligence.

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No Matrix Operation required with Computing in Memory

Deep Learning NN Calculation





$Dn i+1 = \sum_{i} (Wi j \times Dn-1 j)$

Calculation Method Product & Sum Number of Calculation 3 Inputs x 3 Outputs 9 times sum *9 times product* — 1, 0 0 0 Inputs x 1, 0 0 0 Outputs 1, 000, 000 times product + 1, 000, 000 times sum

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G2 for Computing in Memory

input current flow into the G2 memory.

Calculation Method Read-out Number of Read-out One time 3 Inputs X 3 Outputs Simultaneous Read-out of 3 Outputs lines $\begin{bmatrix} 1, 0 & 0 & 0 \end{bmatrix}$ Inputs $x = 1, 0 & 0 & 0 \end{bmatrix}$ Outputs Simultaneous Read-out of 1,000 Outputs lines

